



National Standards Authority of Ireland

IRISH STANDARD

**I.S. EN 61192-5:2007**

ICS 31.190

**WORKMANSHIP REQUIREMENTS FOR  
SOLDERED ELECTRONIC ASSEMBLIES --  
PART 5: REWORK, MODIFICATION AND  
REPAIR OF SOLDERED ELECTRONIC  
ASSEMBLIES (IEC 61192-5:2007 (EQV))**

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EUROPEAN STANDARD

**EN 61192-5**

NORME EUROPÉENNE

EUROPÄISCHE NORM

June 2007

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ICS 31.190

English version

**Workmanship requirements for soldered electronic assemblies -  
Part 5: Rework, modification and repair of soldered electronic assemblies  
(IEC 61192-5:2007)**

Exigences relatives à la qualité  
d'exécution des assemblages  
électroniques brasés -  
Partie 5: Retouche, modification  
et réparation des assemblages  
électroniques brasés  
(CEI 61192-5:2007)

Anforderungen an die Ausführungsqualität  
von Lötbaugruppen -  
Teil 5: Nacharbeit, Änderungen  
und Reparatur von gelöteten  
elektronischen Baugruppen  
(IEC 61192-5:2007)

This European Standard was approved by CENELEC on 2007-06-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

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## Foreword

The text of document 91/652/FDIS, future edition 1 of IEC 61192-5, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61192-5 on 2007-06-01.

The following dates were fixed:

- latest date by which the EN has to be implemented  
at national level by publication of an identical  
national standard or by endorsement (dop) 2008-03-01
- latest date by which the national standards conflicting  
with the EN have to be withdrawn (dow) 2010-06-01

Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the International Standard IEC 61192-5:2007 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61760-1	NOTE	Harmonized as EN 61760-1:2006 (not modified).
ISO 9000	NOTE	Harmonized as EN ISO 9000:2005 (not modified).
ISO 9001	NOTE	Harmonized as EN ISO 9001:2000 (not modified).
ISO 9453	NOTE	Harmonized as EN ISO 9453:2006 (not modified).
ISO 9454-1	NOTE	Harmonized as EN 29454-1:2003 (not modified).

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	- <sup>1)</sup>	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	2006 <sup>2)</sup>
IEC 61190-1-1	- <sup>1)</sup>	Attachment materials for electronic assembly - Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly	EN 61190-1-1	2002 <sup>2)</sup>
IEC 61190-1-2	- <sup>1)</sup>	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering paste for high-quality interconnects in electronics assembly	EN 61190-1-2	2007
IEC 61190-1-3	- <sup>1)</sup>	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	2007
IEC 61191-1	1998	Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	1998
IEC 61191-2	1998	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	1998
IEC 61191-3	- <sup>1)</sup>	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	1998 <sup>2)</sup>

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<sup>1)</sup> Undated reference.

<sup>2)</sup> Valid edition at date of issue.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61191-4	- <sup>1)</sup>	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	1998 <sup>2)</sup>
IEC 61192-1	- <sup>1)</sup>	Workmanship requirements for soldered electronic assemblies - Part 1: General	EN 61192-1	2003 <sup>2)</sup>
IEC 61192-2	- <sup>1)</sup>	Workmanship requirements for soldered electronic assemblies - Part 2: Surface-mount assemblies	EN 61192-2	2003 <sup>2)</sup>
IEC 61192-3	- <sup>1)</sup>	Workmanship requirements for soldered electronic assemblies - Part 3: Through-hole mount assemblies	EN 61192-3	2003 <sup>2)</sup>
IEC 61192-4	- <sup>1)</sup>	Workmanship requirements for soldered electronic assemblies - Part 4: Terminal assemblies	EN 61192-4	2003 <sup>2)</sup>
IEC 61193-1	- <sup>1)</sup>	Quality assessment systems - Part 1: Registration and analysis of defects on printed board assemblies	EN 61193-1	2002 <sup>2)</sup>
IEC 61249	Series	Materials for printed boards and other interconnecting structures	EN 61249	Series

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